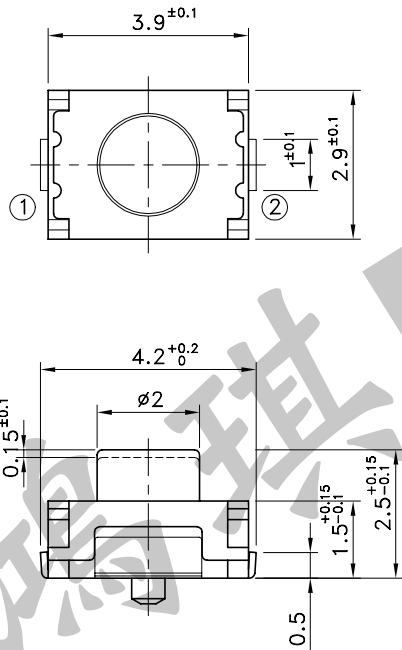
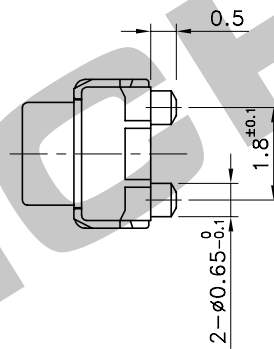


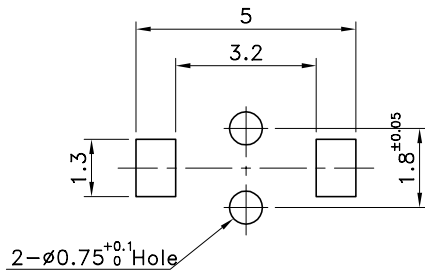
6	Cover tape	Polyimide	t=25 $\mu$ m (Adhesive 25 $\mu$ m)
5	Cover	Stainless Steel	
4	Stem	Polyamide	
3	Contact	Stainless Steel	Ag-Clad 0.5 $\mu$ m
2	Terminal	Phosphor Bronze	Ag-Clad 0.5 $\mu$ m
1	Base	PPS (Polyphenylene Sulfide)	With Glass
No.	Parts	Material	Remarks



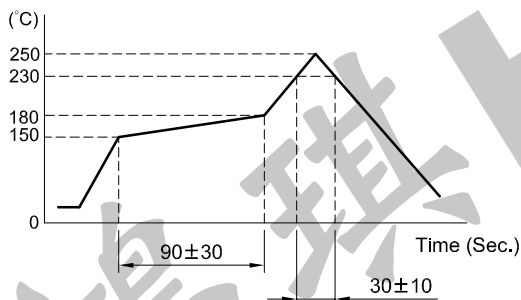
P.C.B TERMINAL POSITION



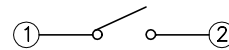
CIRCUIT ARRANGEMENT



REFLOW SOLDERING CONDITIONS



Pb Free Soldering



SPECIFICATIONS

- |                                |  |
|--------------------------------|--|
| 1. Rating                      | :DC 12V 50mA                               |
| 2. Contact Resistance          | :100m $\Omega$ Max.                        |
| 3. Insulation Resistance       | :100M $\Omega$ Min.                        |
| 4. Dielectric Strength         | :AC 100V for 1 minute                      |
| 5. Operating Force             | :160±50gf                                  |
| 6. Stroke                      | :0.15±0.1 mm.                              |
| 7. Life                        | :100,000 Cycles                            |
| 8. Taping                      | :4,000 Pcs/Reel                            |
| 9. Operating Temperature Range | :-20~+70°C                                 |
| 10. Reflow soldering           | : According Reflow Profile<br>Max. 2 Times |

REVISION: \_\_\_\_\_ DATE: \_\_\_\_\_ REVISION: \_\_\_\_\_ DATE: \_\_\_\_\_

UNIT:mm THIRD ANGLE PROJECTION METHOD TOL. UNLESS OTHERWISE STATED: ±0.3 CODE NO.:HCH-249-1

ISSUED	CONFIRMED	<b>HORNG CHIH</b> 鴻琪股份有限公司	PART NO.
<i>Elvis</i> 2004.11.30	<i>Joey</i> 2004.11.30		<b>STS-062</b>